

REVISIONS					
LTR	DESCRIPTION	DATE	REV.	CHKD.	APVD.
△x1	Add recommend PCB thickness	2013.05.14	劉秀慧	郭素玲	郭遠峰
△x7	Add cap drawing and dimension	2013.05.16	劉秀慧	郭素玲	郭遠峰
△x2	Modify the appearance and cap dimension(ECR NO.C03130479)	2013.06.03	劉秀慧	郭素玲	郭遠峰
△x1	Modify the cap dimension (ECR NO.C03130487)	2013.09.27	李阮龍	郭素玲	郭遠峰
△x2	Modify the remark(ECR No.C03150545)	2015.05.08	李阮龍	黃健瑋	郭遠峰

: Pad Area
 PCB Layout Dimension (Tolerance:±0.05)
 (Recommend min. Dimension)(Bottom View)
 △ Recommend PCB (t=1.2) Layout

6	CAP	1	High Temperature Thermoplastic	Black
5	CLIP	2	Ferro Alloy t=0.60	MFCu2μm-Sn3μm
4	TERMINAL (1)	1	Copper Alloy t=0.50	MBCu2μm-Sn3μm
3	BREAK TERMINAL (3)	1	Brass t=0.40	MBCu2μm-Sn3μm
2	SPRING (2)	1	Copper Alloy t=0.25	MBNi1μm-Sn3μm
1	HOUSING	1	High Temperature Thermoplastic	Black

LTR	PART NAME	Q'TY	MATERIAL	REMARK
120~315	±0.50	DWN	劉秀慧	DATE 2013.05.13
30~120	±0.35	DSND	劉秀慧	DATE 2013.05.13
6~30	±0.22	CHKD	郭素玲	DATE 2013.05.13
BELOW 6	±0.16	APVD	郭遠峰	DATE 2013.05.13
DIMENSION TOLERANCE				KUNMING ELECTRONICS CO.,LTD.
				SCALE 2.5/1
				PROJECTION
				NAME DC JACK
				CAT. NO. KM02027CBPT
				DWN.NO. A-02027CBPT
				1/2
				006

The raw material specified by Sony should meet SS-00259 requirement of the latest version. When such material is used, it should be supplied by Sony designated suppliers.

1

2

3

4

5

6

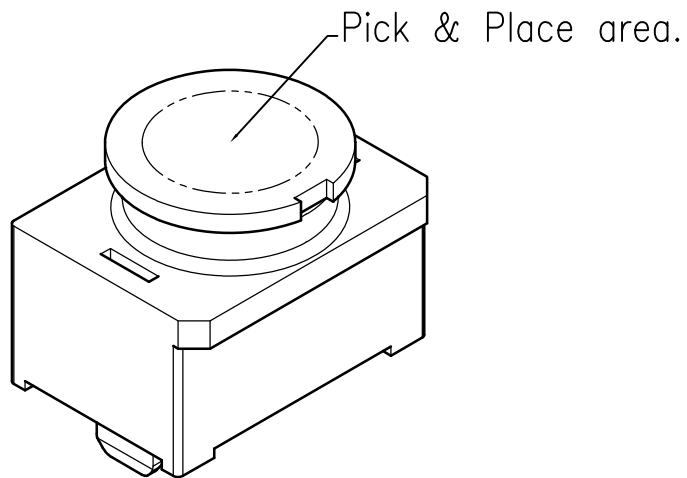
A

B

C

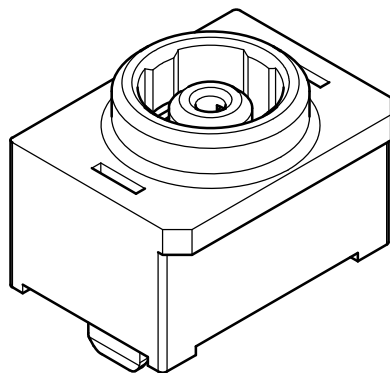
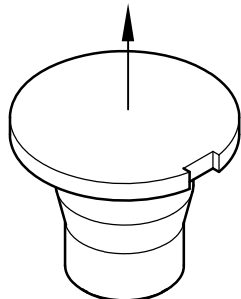
D

E



Before soldering process

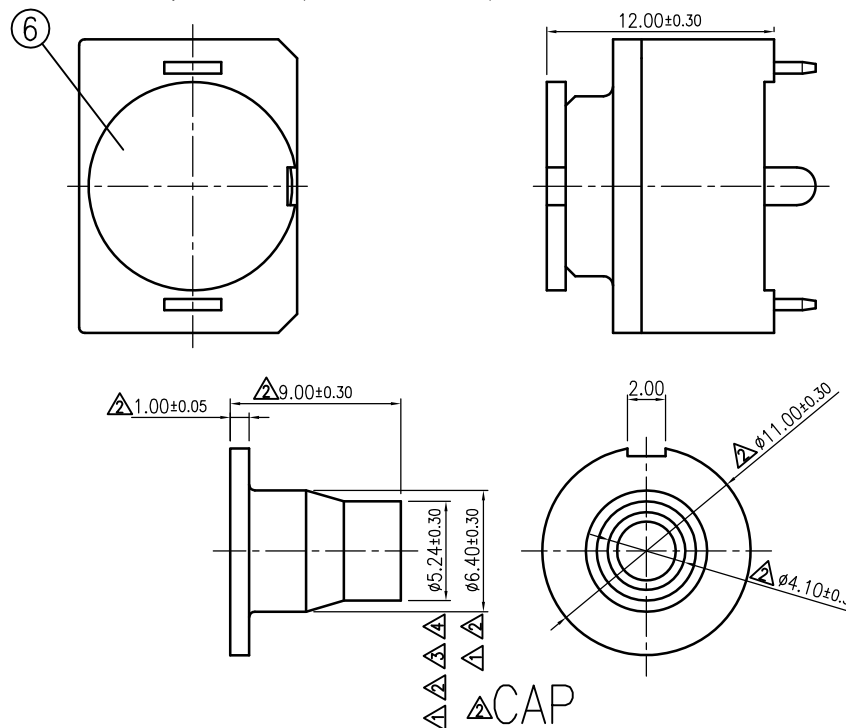
Remove the cap



After soldering process

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DIMENSION TOLERANCE				KUNMING ELECTRONICS CO.,LTD.	NAME DC JACK
				DWN.NO.	CAT. NO.
				A-02027CBPT	KM02027CBPT
				2/2	006

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